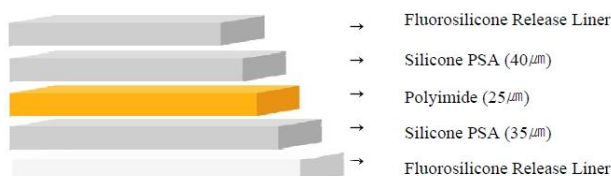


FS-930H is silicon-adhesive tape designed to be used in high-temperature lead free soldering process for flexible circuit board.

The polyimide base film and the selected silicon adhesive make it possible to withstand more than 10 minutes at 250°C soldering process.



The specially designed silicon adhesive does not lose its peeling strength even after many times of soldering cycles and still does not leave residuals. The product is supplied in strip form in customer requested widths to make it easy applying quickly at soldering process.



Technical data (Stand Dec. 2018)

Properties	Unit, Condition	Value (typical)
Base film thickness	µm	25
Total thickness	µm	100
Peel strength L side	gf/in	800
Peel strength H side	gf/in	800
Elongation at break	%	60
Tensile strength	kg/in	12
Temperature resistance	°C	250 (10 min.)
Breakdown voltage	kV	5
Maximum width	mm	500
Storing condition	°C / %	25 ± 5 / 40 ± 20